

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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 $V_{RRM}$ 1400 V **Thyristor** 

60 A

1,14 V

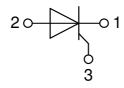
Single Thyristor

Part number

CS60-14io1



Backside: anode



## Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

## **Applications:**

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: PLUS247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

#### Terms \_Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

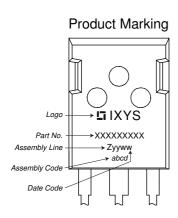
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.



	<b>-</b>			Ì -	1	6	
Symbol	Definition	Conditions		min.	typ.	max.	Uni
V <sub>RSM/DSM</sub>	max. non-repetitive reverse/forwa	ard blocking voltage	$T_{VJ} = 25^{\circ}C$			1500	١
V <sub>RRM/DRM</sub>	max. repetitive reverse/forward bl		$T_{VJ} = 25^{\circ}C$			1400	١
I <sub>R/D</sub>	reverse current, drain current	$V_{R/D} = 1400 \text{ V}$	$T_{VJ} = 25^{\circ}C$			200	μA
		$V_{R/D} = 1400 V$	$T_{VJ} = 140$ °C			10	m <i>P</i>
V <sub>T</sub>	forward voltage drop	I <sub>T</sub> = 60 A	$T_{VJ} = 25^{\circ}C$			1,18	٧
		$I_{T} = 120 \text{ A}$				1,44	\
		$I_T = 60 \text{ A}$	T <sub>vJ</sub> = 125°C			1,14	٧
		$I_{T} = 120 \text{ A}$				1,46	\
I <sub>TAV</sub>	average forward current	T <sub>c</sub> = 110°C	T <sub>v.i</sub> = 140°C			60	Α
I <sub>T(RMS)</sub>	RMS forward current	180° sine				75	A
V <sub>T0</sub>	threshold voltage		T <sub>v.1</sub> = 140°C			0,82	٧
r <sub>T</sub>	slope resistance	oss calculation only	VJ			5,3	mΩ
R <sub>thJC</sub>	thermal resistance junction to cas	20				0,32	K/W
R <sub>thCH</sub>	thermal resistance junction to cas				0,15	0,02	K/W
			T <sub>C</sub> = 25°C		0,10	360	W
P <sub>tot</sub>	total power dissipation	+ 10 may (FO LIT) sing					:
I <sub>TSM</sub>	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			1,40	k/
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1,51	k/
		t = 10  ms; (50  Hz),  sine	$T_{VJ} = 140$ °C			1,19	k/
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1,29	k/
l²t	value for fusing	t = 10  ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			9,80	kA <sup>2</sup> s
		t = 8.3  ms; (60 Hz), sine	$V_R = 0 V$			9,49	kA <sup>2</sup> s
		t = 10  ms; (50  Hz),  sine	$T_{VJ} = 140$ °C			7,08	kA <sup>2</sup> s
		t = 8,3  ms; (60 Hz), sine	$V_R = 0 V$			6,87	kA <sup>2</sup> s
<b>C</b> <sub>J</sub>	junction capacitance	$V_R = 400 V$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		74		рF
P <sub>GM</sub>	max. gate power dissipation	t <sub>P</sub> = 30 μs	T <sub>C</sub> = 140°C			10	W
	, ,	$t_P = 300 \mu s$				5	W
$P_{GAV}$	average gate power dissipation	•				0,5	W
(di/dt) <sub>cr</sub>	critical rate of rise of current	T <sub>v.i</sub> = 140 °C; f = 50 Hz re	enetitive L = 180 A			150	!
(di/dt/cr		$t_p = 200 \mu\text{s}; di_G/dt = 0.3 \text{A/}\mu\text{s}; -$	•			100	π
						E00	Λ/1.6
(1 (1)			on-repet., $I_T = 60 \text{ A}$				A/μs
(dv/dt) <sub>cr</sub>	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	T <sub>VJ</sub> = 140°C			1000	V/μs
		R <sub>GK</sub> = ∞; method 1 (linear volta					
$V_{GT}$	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			1,5	٧
			$T_{VJ} = -40$ °C			1,6	٧
I <sub>GT</sub>	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			100	m <i>P</i>
			$T_{VJ} = -40$ °C			200	m <i>P</i>
V <sub>GD</sub>	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 140^{\circ}C$			0,2	٧
I <sub>GD</sub>	gate non-trigger current					10	m <i>P</i>
I <sub>L</sub>	latching current	t <sub>n</sub> = 10 μs	T <sub>VJ</sub> = 25°C			450	m/
		$I_{G} = 0.45 \text{A};  di_{G}/dt = 0.45 \text{A}/\mu s$	3				
I <sub>H</sub>	holding current	$V_D = 6 \text{ V } R_{GK} = \infty$	T <sub>vJ</sub> = 25°C			200	m <i>A</i>
•н t <sub>gd</sub>	gate controlled delay time	$V_{D} = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25$ °C			2	με
<b>∙</b> gd	gate controlled delay tille					_	με
_		$I_G = 0.45 \text{ A}; \text{ di}_G/\text{dt} = 0.45 \text{ A}/\mu\text{s}$ $V_R = 100 \text{ V}; I_T = 60 \text{ A}; V = \frac{2}{3}$			150		με
t <sub>q</sub>	turn-off time						



Package PLUS247				Ratings			
Symbol	Definition Condit	ions	min.	typ.	max.	Unit	
I <sub>RMS</sub>	RMS current per term	ninal			70	Α	
T <sub>VJ</sub>	virtual junction temperature		-40		140	°C	
T <sub>op</sub>	operation temperature		-40		125	°C	
T <sub>stg</sub>	storage temperature		-40		140	°C	
Weight				6		g	
F <sub>c</sub>	mounting force with clip		20		120	N	
d <sub>Spp/App</sub>	araanaga diatanaa an ayrfaaa l atriking diatanaa thra	terminal to terminal	5,5			mm	
d <sub>Spb/Apb</sub>	creepage distance on surface   striking distance thro	terminal to backside	5,5			mm	



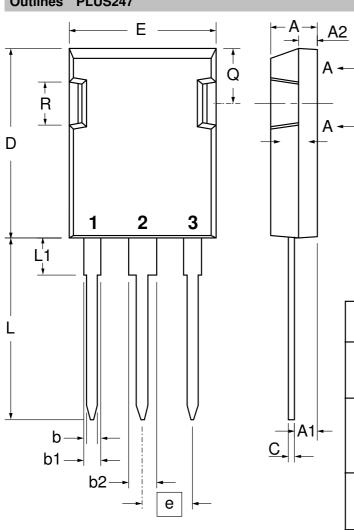
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CS60-14io1	CS60-14io1	Tube	30	507901

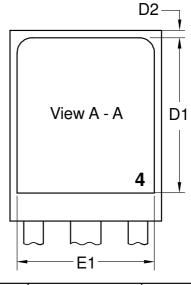
Similar Part	Package	Voltage class
CS60-12io1	PLUS247 (3)	1200
CS60-16io1	PLUS247 (3)	1600

Equiva	alent Circuits for	Simulation	* on die level	$T_{VJ} = 140 ^{\circ}\text{C}$
$I \rightarrow V_0$	)— <u>R</u> o	Thyristor		
V <sub>0 max</sub>	threshold voltage	0,82		V
$R_{0\;max}$	slope resistance *	3		$m\Omega$

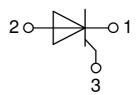


# **Outlines PLUS247**





Sym.	Inches		Millimeter		
	min.	max.	min.	max.	
Α	0.190	0.205	4.83	5.21	
A1	0.090	0.100	2.29	2.54	
A2	0.075	0.085	1.91	2.16	
b	0.045	0.055	1.14	1.40	
b1	0.075	0.084	1.91	2.13	
b2	0.115	0.123	2.92	3.12	
С	0.024	0.031	0.61	0.80	
D	0.819	0.840	20.80	21.34	
D1	0.515	-	13.07	-	
D2	0.010	0.053	0.51	1.35	
Е	0.620	0.635	15.75	16.13	
E1	0.530	-	13.45	-	
е	0.215	BSC	5.45 BSC		
L	0.780	0.800	19.81	20.32	
L1	0.150	0.170	3.81	4.32	
Q	0.220	0.244	5.59	6.20	
R	0.170	0.190	4.32	4.83	





# **Thyristor**

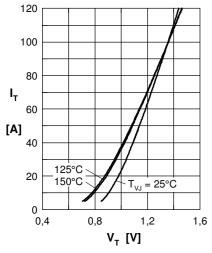


Fig. 1 Forward characteristics

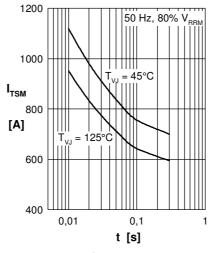


Fig. 2 Surge overload current

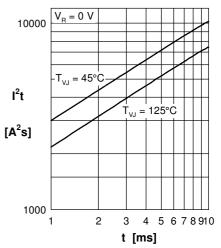


Fig. 3 I<sup>2</sup>t versus time (1-10 ms)

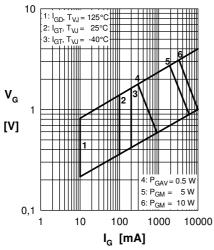


Fig. 4 Gate trigger characteristics

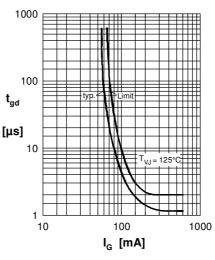


Fig. 5 Gate controlled delay time

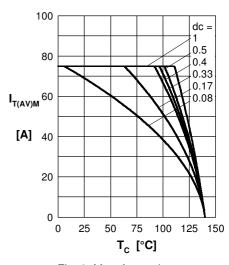


Fig. 6 Max. forward current at case temperature

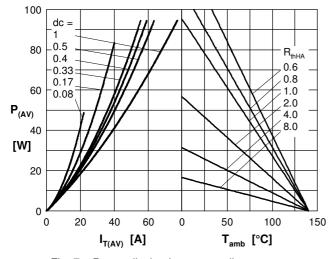


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

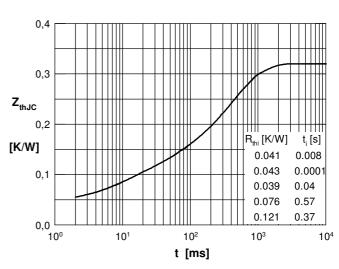


Fig. 8 Transient thermal impedance junction to case